Binary Up/Down Counter

The MC14516B synchronous up/down binary counter is constructed with MOS P-channel and N-channel enhancement mode devices in a monolithic structure.

This counter can be preset by applying the desired value, in binary, to the Preset inputs (P0, P1, P2, P3) and then bringing the Preset Enable (PE) high. The direction of counting is controlled by applying a high (for up counting) or a low (for down counting) to the UP/DOWN input. The state of the counter changes on the positive transition of the clock input.

Cascading can be accomplished by connecting the $\overline{\text{Carry Out}}$ to the $\overline{\text{Carry In}}$ of the next stage while clocking each counter in parallel. The outputs (Q0, Q1, Q2, Q3) can be reset to a low state by applying a high to the reset (R) pin.

This CMOS counter finds primary use in up/down and difference counting. Other applications include: (1) Frequency synthesizer applications where low power dissipation and/or high noise immunity is desired, (2) Analog–to–digital and digital–to–analog conversions, and (3) Magnitude and sign generation.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Speed
- Logic Edge-Clocked Design Count Occurs on Positive Going Edge of Clock
- Single Pin Reset
- Asynchronous Preset Enable Operation
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky Load Over the Rated Temperature Range

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 2.)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 3.)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C



ON Semiconductor

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MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648



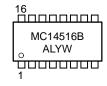


SOIC-16 D SUFFIX CASE 751B





SOEIAJ-16 F SUFFIX CASE 966



Α

= Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

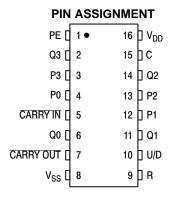
ORDERING INFORMATION

Device	Package	Shipping
MC14516BCP	PDIP-16	2000/Box
MC14516BD	SOIC-16	48/Rail
MC14516BDR2	SOIC-16	2500/Tape & Reel
MC14516BF	SOEIAJ-16	See Note 1.
MC14516BFEL	SOEIAJ-16	See Note 1.

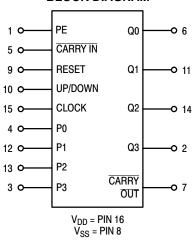
 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



BLOCK DIAGRAM



TRUTH TABLE

Carry In	Up/Down	Preset Enable	Reset	Clock	Action
1	Х	0	0	Х	No Count
0	1	0	0		Count Up
0	0	0	0		Count Down
Х	Х	1	0	Х	Preset
Х	Х	Х	1	Х	Reset

X = Don't Care

NOTE: When counting up, the Carry Out signal is normally high and is low only when Q0 through Q3 are high and Carry In is low. When counting down, Carry Out is low only when Q0 through Q3 and Carry In are low.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			V _{DD}	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ ^(4.)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15		1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11		Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	_	5.0 10 20	_ _ _	0.005 0.010 0.015	5.0 10 20	_	150 300 600	μAdc
Total Supply Current ^(5.) (6 (Dynamic plus Quiesco Per Package) (C _L = 50 pF on all outp buffers switching)	ent,	Ι _Τ	5.0 10 15			$I_{T} = (1$.58 μA/kHz) .20 μA/kHz) .70 μA/kHz)	f + I _{DD}			μAdc

^{4.} Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
5. The formulas given are for the typical characteristics only at 25°C.
6. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.001.

SWITCHING CHARACTERISTICS (7.) $(C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C})$

		All Types				
Characteristic	Symbol	V_{DD}	Min	Typ ^(8.)	Max	Unit
Output Rise and Fall Time $ \begin{array}{l} t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 25 \text{ ns} \\ t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} \\ t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 9.5 \text{ ns} \\ \end{array} $	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_{L} + 230 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_{L} + 97 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) \text{ C}_{L} + 75 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	315 130 100	630 260 200	ns
Clock to $\overline{\text{Carry Out}}$ $\text{t}_{\text{PLH}}, \text{t}_{\text{PHL}} = (1.7 \text{ ns/pF}) \text{ C}_{\text{L}} + 230 \text{ ns}$ $\text{t}_{\text{PLH}}, \text{t}_{\text{PHL}} = (0.66 \text{ ns/pF}) \text{ C}_{\text{L}} + 97 \text{ ns}$ $\text{t}_{\text{PLH}}, \text{t}_{\text{PHL}} = (0.5 \text{ ns/pF}) \text{ C}_{\text{L}} + 75 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	315 130 100	630 260 200	ns
Carry In to Carry Out t_{PLH} , t_{PHL} = (1.7 ns/pF) C_L + 230 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_L + 97 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_L + 75 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	180 80 60	360 160 120	ns
Preset or Reset to Q t_{PLH} , $t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_{L} + 230 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_{L} + 97 \text{ ns}$ t_{PLH} , $t_{PHL} = (0.5 \text{ ns/pF}) \text{ C}_{L} + 75 \text{ ns}$	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	315 130 100	630 360 200	ns
Preset or Reset to $\overline{\text{Carry Out}}$ t_{PLH} , t_{PHL} = (1.7 ns/pF) C_{L} + 465 ns t_{PLH} , t_{PHL} = (0.66 ns/pF) C_{L} + 192 ns t_{PLH} , t_{PHL} = (0.5 ns/pF) C_{L} + 125 ns	t _{PLH} , t _{PHL}	5.0 10 15	_ _ _	550 225 150	1100 450 300	ns
Reset Pulse Width	t _w	5.0 10 15	380 200 160	190 100 80	_ _ _	ns
Clock Pulse Width	t _{WH}	5.0 10 15	350 170 140	200 100 75	_ _ _	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	_ _ _	3.0 6.0 8.0	1.5 3.0 4.0	MHz

^{7.} The formulas given are for the typical characteristics only at 25°C.8. Data labelled "Typ" is not to be used for design purposes but is intended as an Indication of the IC's potential performance.

SWITCHING CHARACTERISTICS (9.) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C}$) (continued)

			All Types			
Characteristic	Symbol	V _{DD}	Min	Typ ^(10.)	Max	Unit
Preset or Reset Removal Time The Preset or Reset signal must be low prior to a positive—going transition of the clock.	t _{rem}	5.0 10 15	650 230 180	325 115 90		ns
Clock Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15	_ _ _	_ _ _	15 5 4	μs
Setup Time Carry In to Clock	t _{su}	5.0 10 15	260 120 100	130 60 50		ns
Hold Time Clock to Carry In	t _h	5.0 10 15	0 20 20	- 60 - 20 0		ns
Setup Time Up/Down to Clock	t _{su}	5.0 10 15	500 200 150	250 100 75		ns
Hold Time Clock to Up/Down	t _h	5.0 10 15	- 70 - 10 0	- 160 - 60 - 40		ns
Setup Time Pn to PE	t _{su}	5.0 10 15	- 40 - 30 - 25	- 120 - 70 - 50		ns
Hold Time PE to Pn	t _h	5.0 10 15	480 420 420	240 210 210		ns
Preset Enable Pulse Width	t _{WH}	5.0 10 15	200 100 80	100 50 40		ns

^{9.} The formulas given are for the typical characteristics only at 25°C.10. Data labelled "Typ" is not to be used for design purposes but is intended as an Indication of the IC's potential performance.

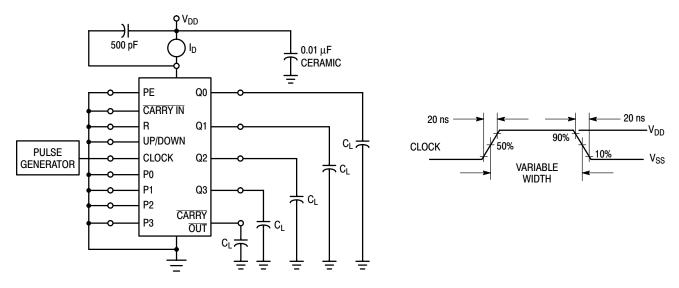
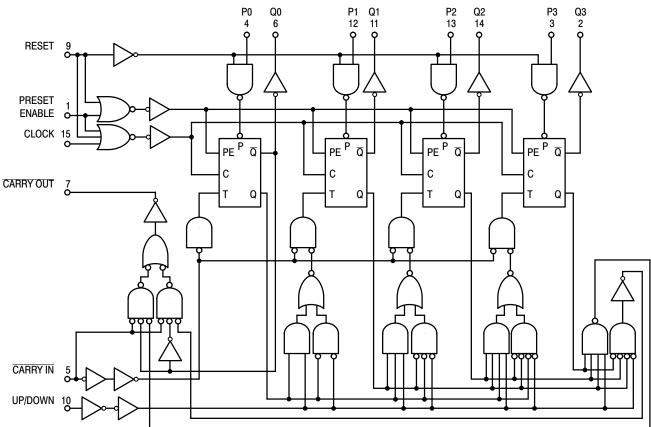
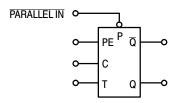


Figure 1. Power Dissipation Test Circuit and Waveform

LOGIC DIAGRAM



TOGGLE FLIP-FLOP



FLIP-FLOP FUNCTIONAL TRUTH TABLE

Preset Enable	Clock	т	Q _{n+1}
1	Х	Х	Parallel In
0	_	0	Q _n
0	_	1	\overline{Q}_n
0	7	Х	Q _n

X = Don't Care

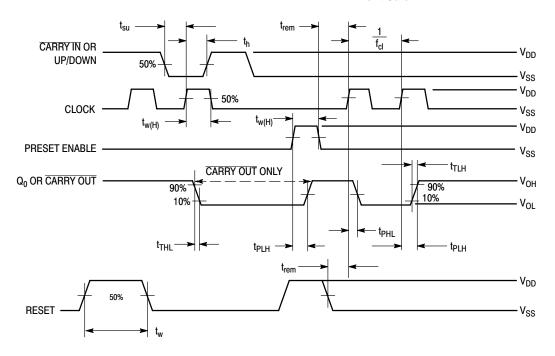


Figure 2. Switching Time Waveforms

PIN DESCRIPTIONS

INPUTS

P0, P1, P2, P3, Preset Inputs (Pins 4, 12, 13, 3) — Data on these inputs is loaded into the counter when PE is taken high

Carry In, (Pin 5) — This active—low input is used when Cascading stages. Carry In is usually connected to Carry Out of the previous stage. While high, Clock is inhibited.

Clock, (Pin 15) — Binary data is incremented or decremented, depending on the direction of count, on the positive transition of this input.

OUTPUTS

Q0, Q1, Q2, Q3, Binary outputs (Pins 6, 11, 14, 2) — Binary data is present on these outputs with Q0 corresponding to the least significant bit.

Carry Out, (Pin 7) — Used when cascading stages, Carry Out is usually connected to Carry In of the next stage. This synchronous output is active low and may also be used to indicate terminal count.

CONTROLS

PE, Preset Enable, (Pin 1) — Asynchronously loads data on the Preset Inputs. This pin is active high and inhibits the clock when high.

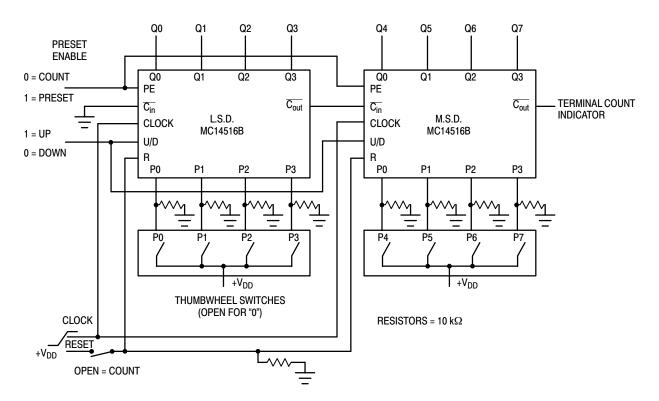
R, Reset, (Pin 9) — Asynchronously resets the Q outputs to a low state. This pin is active high and inhibits the clock when high.

Up/Down, (Pin 10) — Controls the direction of count, high for up count, low for down count.

SUPPLY PINS

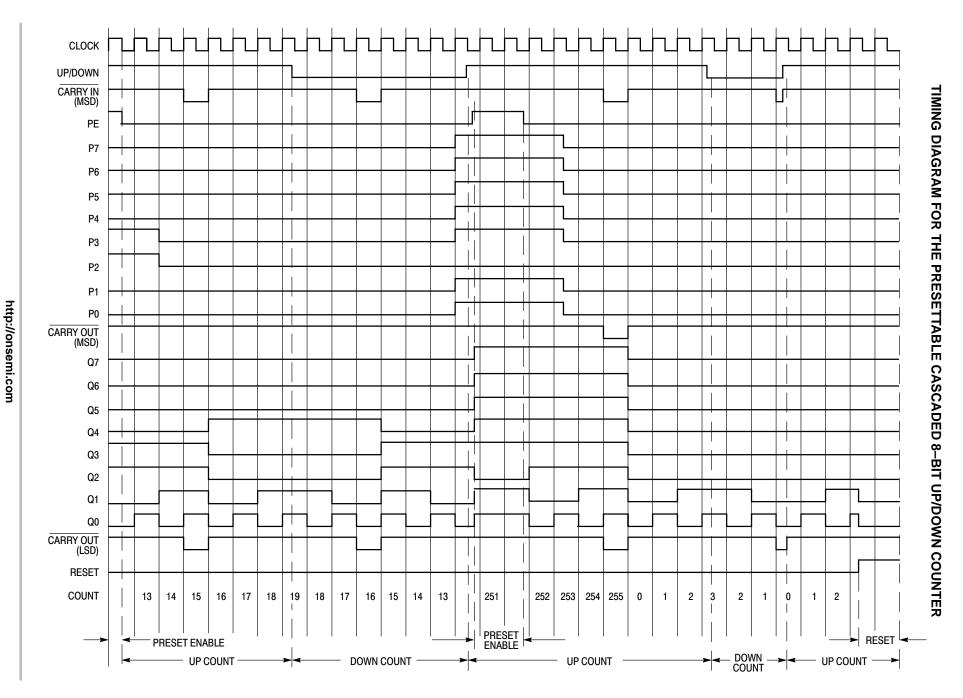
V_{SS}, Negative Supply Voltage, (Pin 8) — This pin is usually connected to ground.

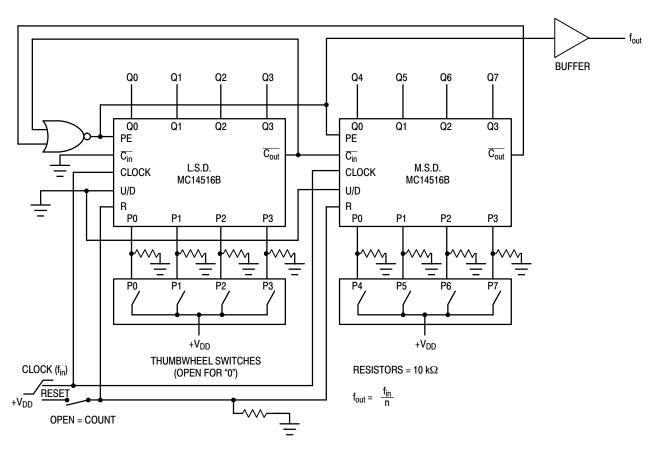
 V_{DD} , Positive Supply Voltage, (Pin 16) — This pin is connected to a positive supply voltage ranging from 3.0 volts to 18.0 volts.



NOTE: The Least Significant Digit (L.S.D.) counts from a preset value once Preset Enable (PE) goes low. The Most Significant Digit (M.S.D.) is disabled while $\overline{C_{in}}$ is high. When the count of the L.S.D. reaches 0 (count down mode) or reaches 15 (count up mode), $\overline{C_{out}}$ goes low for one complete clock cycle, thus allowing the next counter to decrement/increment one count. (See Timing Diagram) The L.S.D. now counts through another cycle (15 clock pulses) and the above cycle is repeated.

Figure 3. Presettable Cascaded 8-Bit Up/Down Counter

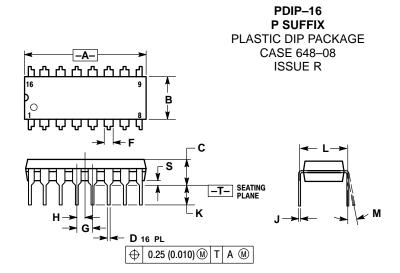




NOTE: The programmable frequency divider can be set by applying the desired divide ratio, in binary, to the preset inputs. For example, the maximum divide ratio of 255 may be obtained by applying a 1111 1111 to the preset inputs P0 to P7. For this divide operation, both counters should be configured in the count down mode. The divide ratio of zero is an undefined state and should be avoided.

Figure 4. Programmable Cascaded Frequency Divider

PACKAGE DIMENSIONS



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION LTO CENTER OF LEADS WHEN FORMED PARALLEL.

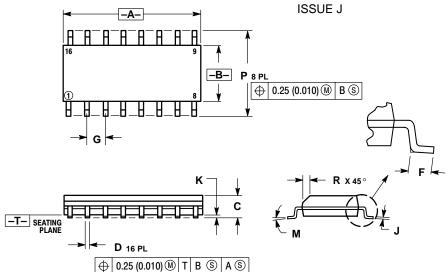
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

SOIC-16 **D SUFFIX**

PLASTIC SOIC PACKAGE CASE 751B-05



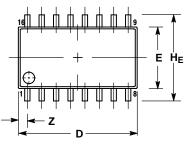
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLEHANCING PER ANY Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- MAXIMUM MOLD FRO HOSIGIA 4.15 (5.655)
 PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (6.065) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

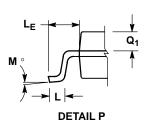
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

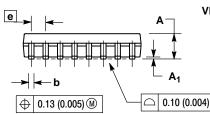
PACKAGE DIMENSIONS

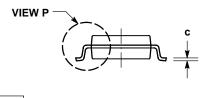
SOEIAJ-16 **F SUFFIX**

PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE O**









NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- CONTROLLING DIMENSION: MILLIMETER. I. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.

 TERMINAL NUMBERS ARE SHOWN FOR
- 4. TEHMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) DAMBAR FRO INJSION STRALL BE USO (0.005)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

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